

Global IC Package Substrates Market 2024 by Manufacturers, Regions, Type and Application, Forecast to 2030

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Abstracts

According to our (Global Info Research) latest study, the global IC Package Substrates market size was valued at USD million in 2023 and is forecast to a readjusted size of USD million by 2030 with a CAGR of % during review period.

IC substrate is a type of carry material for integrated circuit with internal circuit to connect the chips and PCBs. Additionally, the IC substrate can protect the circuit, special line, it is designed for heat dissipation and acts standardized module of IC components. It is one of the most key materials of the IC packaging, and the share of IC substrate for IC packaging is as high as 35-55%.

The major manufacturers that provide IC Package Substrates in China include SCC, Nanya and Access Substrates, etc. The top three manufacturers account for more than 50% of the market share. Among them, WB BGA and FC-CSP accounted for 39% and 38%, respectively. Smartphones and PCs (tablets and laptops) are the most widely used, accounting for 64% and 23%, respectively.

The Global Info Research report includes an overview of the development of the IC Package Substrates industry chain, the market status of Smart Phone (FC-BGA, FC-CSP), PC (tablet and Laptop) (FC-BGA, FC-CSP), and key enterprises in developed and developing market, and analysed the cutting-edge technology, patent, hot applications and market trends of IC Package Substrates.

Regionally, the report analyzes the IC Package Substrates markets in key regions. North America and Europe are experiencing steady growth, driven by government initiatives and increasing consumer awareness. Asia-Pacific, particularly China, leads



the global IC Package Substrates market, with robust domestic demand, supportive policies, and a strong manufacturing base.

Key Features:

The report presents comprehensive understanding of the IC Package Substrates market. It provides a holistic view of the industry, as well as detailed insights into individual components and stakeholders. The report analysis market dynamics, trends, challenges, and opportunities within the IC Package Substrates industry.

The report involves analyzing the market at a macro level:

Market Sizing and Segmentation: Report collect data on the overall market size, including the sales quantity (K Sqm), revenue generated, and market share of different by Type (e.g., FC-BGA, FC-CSP).

Industry Analysis: Report analyse the broader industry trends, such as government policies and regulations, technological advancements, consumer preferences, and market dynamics. This analysis helps in understanding the key drivers and challenges influencing the IC Package Substrates market.

Regional Analysis: The report involves examining the IC Package Substrates market at a regional or national level. Report analyses regional factors such as government incentives, infrastructure development, economic conditions, and consumer behaviour to identify variations and opportunities within different markets.

Market Projections: Report covers the gathered data and analysis to make future projections and forecasts for the IC Package Substrates market. This may include estimating market growth rates, predicting market demand, and identifying emerging trends.

The report also involves a more granular approach to IC Package Substrates:

Company Analysis: Report covers individual IC Package Substrates manufacturers, suppliers, and other relevant industry players. This analysis includes studying their financial performance, market positioning, product portfolios, partnerships, and strategies.

Consumer Analysis: Report covers data on consumer behaviour, preferences, and



attitudes towards IC Package Substrates This may involve surveys, interviews, and analysis of consumer reviews and feedback from different by Application (Smart Phone, PC (tablet and Laptop)).

Technology Analysis: Report covers specific technologies relevant to IC Package Substrates. It assesses the current state, advancements, and potential future developments in IC Package Substrates areas.

Competitive Landscape: By analyzing individual companies, suppliers, and consumers, the report present insights into the competitive landscape of the IC Package Substrates market. This analysis helps understand market share, competitive advantages, and potential areas for differentiation among industry players.

Market Validation: The report involves validating findings and projections through primary research, such as surveys, interviews, and focus groups.

Market Segmentation

IC Package Substrates market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value.

Market segment k	VC	Type
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FC-BGA

FC-CSP

WB BGA

WB CSP

RF Module

Others

Market segment by Application



Smart Phone
PC (tablet and Laptop)
Wearable Device
Others
Major players covered
Unimicron
Ibiden
Nan Ya PCB
Shinko Electric Industries
Kinsus Interconnect Technology
AT&S
Semco
Kyocera
TOPPAN
Zhen Ding Technology
Daeduck Electronics
ASE Material
LG InnoTek
Simmtech



Shennan Circuit

Shenzhen Fastprint Circuit Tech

ACCESS

Suntak Technology

National Center for Advanced Packaging (NCAP China)

Huizhou China Eagle Electronic Technology

DSBJ

Shenzhen Kinwong Electronic

AKM Meadville

Victory Giant Technology

Market segment by region, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe IC Package Substrates product scope, market overview, market estimation caveats and base year.



Chapter 2, to profile the top manufacturers of IC Package Substrates, with price, sales, revenue and global market share of IC Package Substrates from 2019 to 2024.

Chapter 3, the IC Package Substrates competitive situation, sales quantity, revenue and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the IC Package Substrates breakdown data are shown at the regional level, to show the sales quantity, consumption value and growth by regions, from 2019 to 2030.

Chapter 5 and 6, to segment the sales by Type and application, with sales market share and growth rate by type, application, from 2019 to 2030.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value and market share for key countries in the world, from 2017 to 2023.and IC Package Substrates market forecast, by regions, type and application, with sales and revenue, from 2025 to 2030.

Chapter 12, market dynamics, drivers, restraints, trends and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of IC Package Substrates.

Chapter 14 and 15, to describe IC Package Substrates sales channel, distributors, customers, research findings and conclusion.



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